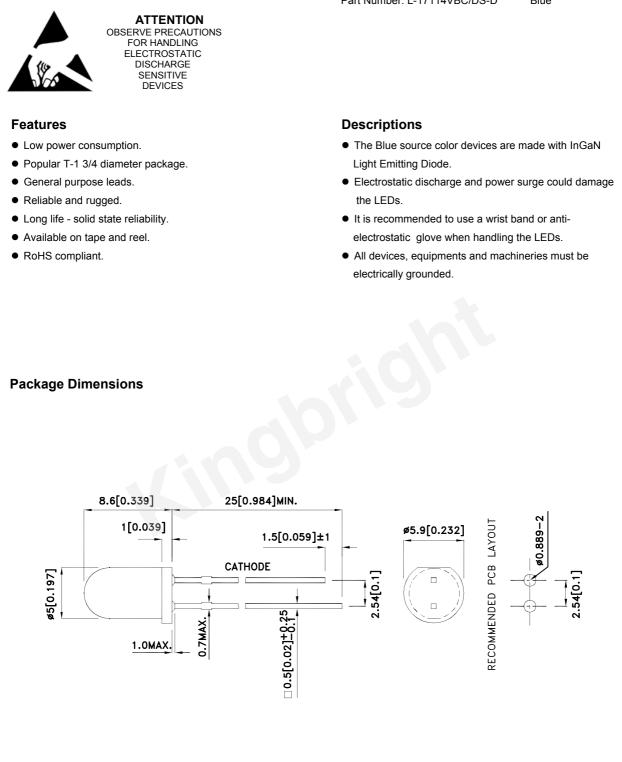
T-1 3/4 (5mm) SOLID STATE LAMP

Part Number: L-17114VBC/DS-D Blue



Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is ±0.25(0.01") unless otherwise noted.

Lead spacing is measured where the leads emerge from the package.
The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

DATE: APR/29/2014 DRAWN: L.Q.Xie

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Selection Guide

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-17114VBC/DS-D	Blue (InGaN)	Water Clear	6000	9000	15°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	465		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Blue	470		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	22		nm	IF=20mA
С	Capacitance	Blue	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue	3.3	4	V	I⊧=20mA
lr	Reverse Current	Blue		50	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

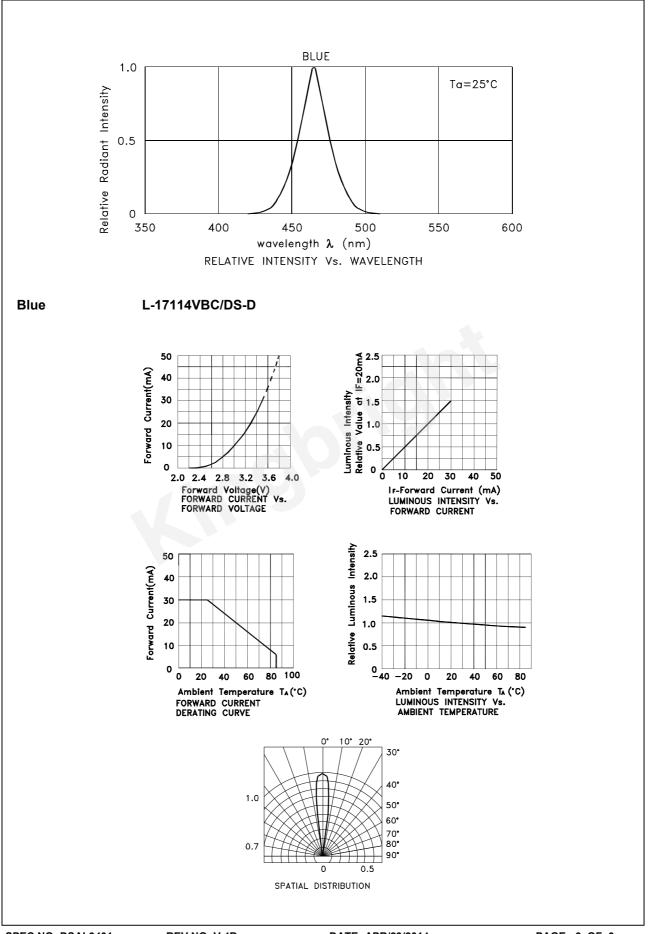
Parameter	Blue	Units		
Power dissipation	120	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

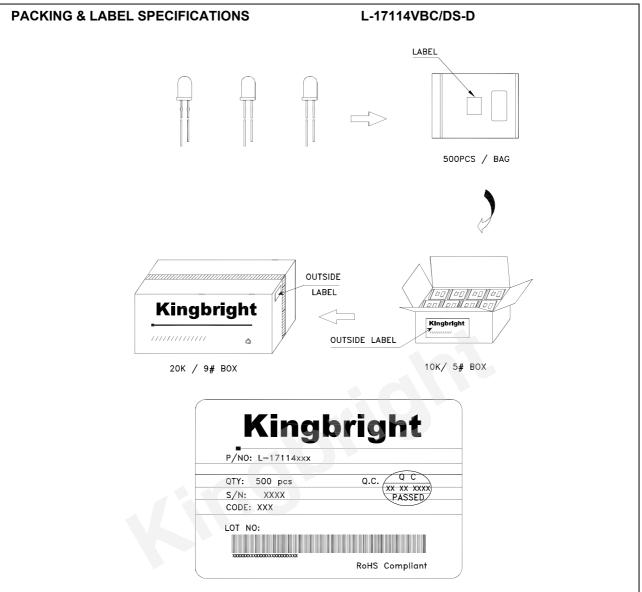
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.



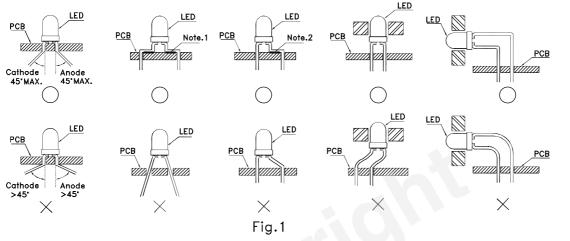


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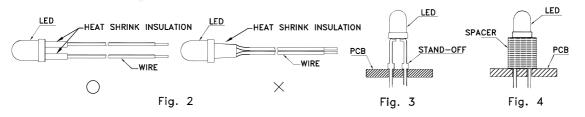
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



" \bigcirc " Correct mounting method " \times " Incorrect mounting method

- When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

